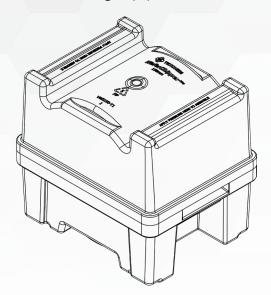
WaferShipper

VWS: Vertical WaferShipper

Texchem's VWS is an industry accepted design providing superior protection for critical wafer handling requirements. The VWS is designed to match the cassette package size that are widely used in the industry and are compatible with automated wafer loading equipment



Application

Bare/ Prime Wafer Shipping

Advantages

Made with Ultra Clean Material Superior Box Fitting and Dimensional Stability Proven Industrial Standard Design

Shipper Material

Wafer Grade Ultra Clean PP

Wafer Size

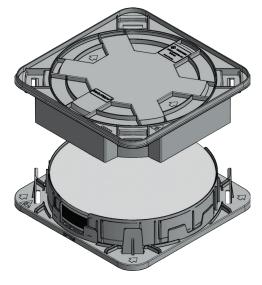
100mm (4") 150mm (6") 200mm (8")

Wafer Capacity

25 Wafers

HWS-RM: Horizontal WaferShipper

Texchem's HWS-RM provide superior protection and substantial freight cost savings. The product are designed to meet SEMI standard load port specifications to be compatible with automated wafer packing and sorting equipment.



Application

Processed Wafer Shipping

Advantages

Superior Wafer Protection Substantial Freight Cost Reduction Substantial Space Saving Compounded ESD Property

Shipper Material

Wafer Grade Clean PP (Conductive)

Wafer Size

200mm (8") 300mm (12")

Wafer Capacity

25 wafers



TEXCHEM-PACK (PP) SDN. BHD.

Part of Lot 1241, Phase III, Bayan Lepas Free Industrial Zone 11900 Bayan Lepas, Penang, Malaysia

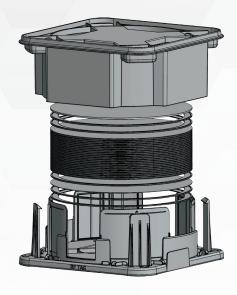
Tel: 604 643 8661

Email: txppgsales@texchem-pack.com

WaferShipper

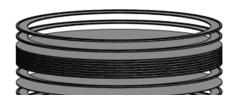
BHWS-RM: Bumped Horizontal Wafer Shipper

BHWS-RM is designed for transportation of 25 bumped or sensitive surface wafers with Wafer Separator Rings (WSR).BHWS-RM is paired with our WSR to reduce wafer surface contact during transportation.



WSR: Wafer Separator Ring

WSR is designed for transporting Bumped or Sensitive wafer shipping. WSR aim to replace carbon or non-woven interleaves to greatly reduce wafer surface contact and achieve higher cleanliness and lower particle counts. The contact is only made with SEMI standard exclusion zone.



WCR: Wafer Compliance Ring

WCR aim to replace Foam Cushion to achieve higher cleanliness and lower particle counts. The contact is only made with SEMI standard exclusion zone.



Application

Bumped Wafer Shipping Sensitive Wafer Shipping

Advantages

Less Wafer Surface Contact Superior Wafer Protection Substantial Freight Cost Reduction Substantial Space Saving Compounded ESD Property

Shipper Material

Wafer Grade Clean PP (Conductive)

Wafer Size

200mm (8") 300mm (12")

Wafer Capacity

25 wafers

Application

To Replace Interleaves

Advantages

Lower Particle Count Less Humidity Absorption Less Wafer Surface Contact

Wafer Size

200mm (8") 300mm (12")

Application

To Replace Foam Cushion

Advantages

Lower Particle Count Less Humidity Absorption Less Wafer Surface Contact

Wafer Size

300mm (12")



TEXCHEM-PACK (PP) SDN. BHD.

Part of Lot 1241, Phase III, Bayan Lepas Free Industrial Zone 11900 Bayan Lepas, Penang, Malaysia Tel: 604 643 8661

Email: txppgsales@texchem-pack.com